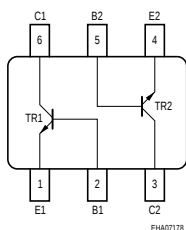
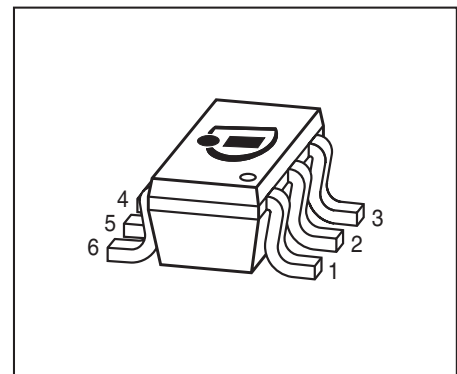


## NPN Silicon AF Transistor Array

- For AF stages and driver applications
- High current gain
- Low collector-saturation voltage
- Two (galvanic) internal isolated transistors with good matching in one package
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



| Type   | Marking | Pin Configuration |      |      |      |      |      | Package |
|--------|---------|-------------------|------|------|------|------|------|---------|
| BC817U | 6Bs     | 1=E1              | 2=B1 | 3=C2 | 4=E2 | 5=B2 | 6=C1 | SC74    |

## Maximum Ratings

| Parameter                                                | Symbol    | Value       | Unit             |
|----------------------------------------------------------|-----------|-------------|------------------|
| Collector-emitter voltage                                | $V_{CEO}$ | 45          | V                |
| Collector-base voltage                                   | $V_{CBO}$ | 50          |                  |
| Emitter-base voltage                                     | $V_{EBO}$ | 5           |                  |
| Collector current                                        | $I_C$     | 500         | mA               |
| Peak collector current, $t_p \leq 10 \text{ ms}$         | $I_{CM}$  | 1000        |                  |
| Base current                                             | $I_B$     | 100         |                  |
| Peak base current                                        | $I_{BM}$  | 200         |                  |
| Total power dissipation-<br>$T_S \leq 115^\circ\text{C}$ | $P_{tot}$ | 330         | mW               |
| Junction temperature                                     | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                                      | $T_{stg}$ | -65 ... 150 |                  |

### Thermal Resistance

| Parameter                                | Symbol     | Value      | Unit |
|------------------------------------------|------------|------------|------|
| Junction - soldering point <sup>1)</sup> | $R_{thJS}$ | $\leq 105$ | K/W  |

### Electrical Characteristics at $T_A = 25^\circ\text{C}$ , unless otherwise specified

| Parameter | Symbol | Values |      |      | Unit |
|-----------|--------|--------|------|------|------|
|           |        | min.   | typ. | max. |      |

### DC Characteristics

|                                                                                                                                       |               |            |          |           |               |
|---------------------------------------------------------------------------------------------------------------------------------------|---------------|------------|----------|-----------|---------------|
| Collector-emitter breakdown voltage<br>$I_C = 10\text{ mA}$ , $I_B = 0$                                                               | $V_{(BR)CEO}$ | 45         | -        | -         | V             |
| Collector-base breakdown voltage<br>$I_C = 10\text{ }\mu\text{A}$ , $I_E = 0$                                                         | $V_{(BR)CBO}$ | 50         | -        | -         |               |
| Emitter-base breakdown voltage<br>$I_E = 10\text{ }\mu\text{A}$ , $I_C = 0$                                                           | $V_{(BR)EBO}$ | 5          | -        | -         |               |
| Collector-base cutoff current<br>$V_{CB} = 25\text{ V}$ , $I_E = 0$<br>$V_{CB} = 25\text{ V}$ , $I_E = 0$ , $T_A = 150^\circ\text{C}$ | $I_{CBO}$     | -<br>-     | -<br>-   | 0.1<br>50 | $\mu\text{A}$ |
| Emitter-base cutoff current<br>$V_{EB} = 4\text{ V}$ , $I_C = 0$                                                                      | $I_{EBO}$     | -          | -        | 100       | nA            |
| DC current gain <sup>2)</sup><br>$I_C = 100\text{ mA}$ , $V_{CE} = 1\text{ V}$<br>$I_C = 300\text{ mA}$ , $V_{CE} = 1\text{ V}$       | $h_{FE}$      | 160<br>100 | 250<br>- | 400<br>-  | -             |
| Collector-emitter saturation voltage <sup>2)</sup><br>$I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$                                    | $V_{CEsat}$   | -          | -        | 0.7       | V             |
| Base emitter saturation voltage <sup>2)</sup><br>$I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$                                         | $V_{BEsat}$   | -          | -        | 1.2       |               |

### AC Characteristics

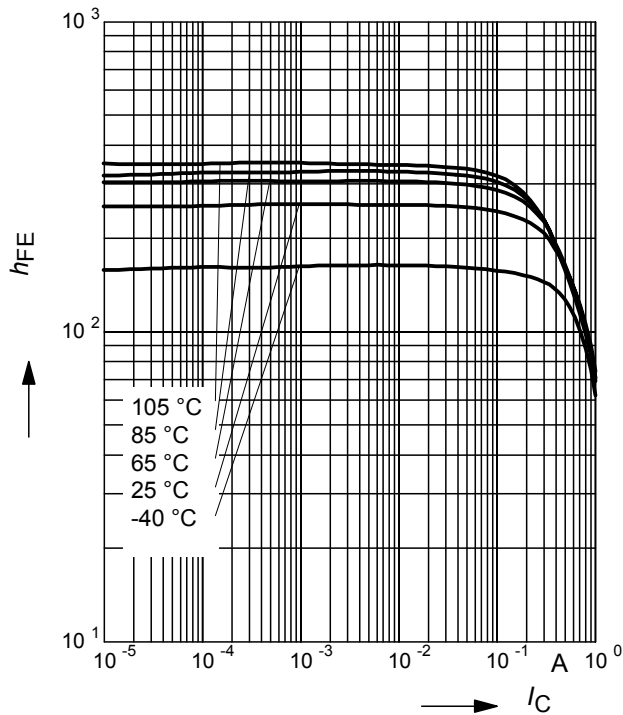
|                                                                                             |          |   |     |   |     |
|---------------------------------------------------------------------------------------------|----------|---|-----|---|-----|
| Transition frequency<br>$I_C = 50\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $f = 100\text{ MHz}$ | $f_T$    | - | 170 | - | MHz |
| Collector-base capacitance<br>$f = 1\text{ MHz}$ , $V_{BE} = 10\text{ V}$                   | $C_{cb}$ | - | 6   | - | pF  |
| Emitter-base capacitance<br>$V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$                    | $C_{eb}$ | - | 60  | - |     |

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

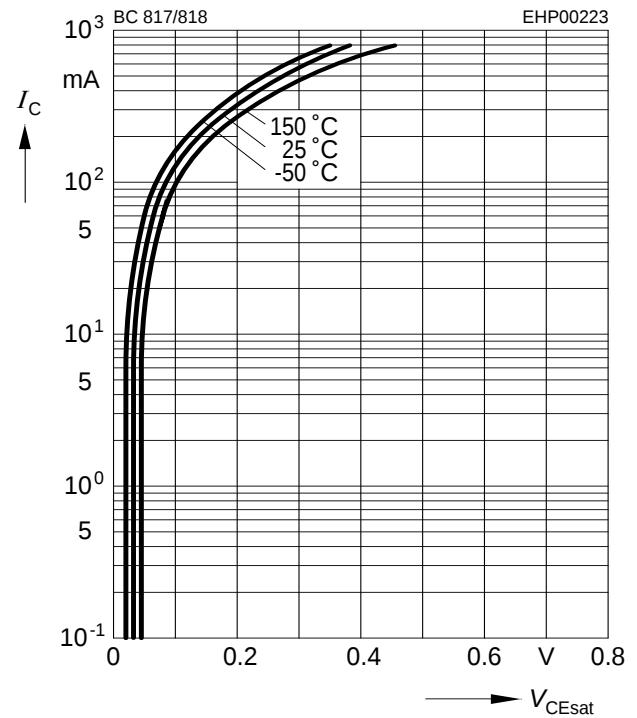
<sup>2)</sup>Pulse test:  $t < 300\mu\text{s}$ ;  $D < 2\%$

**DC current gain  $h_{FE} = f(I_C)$** 

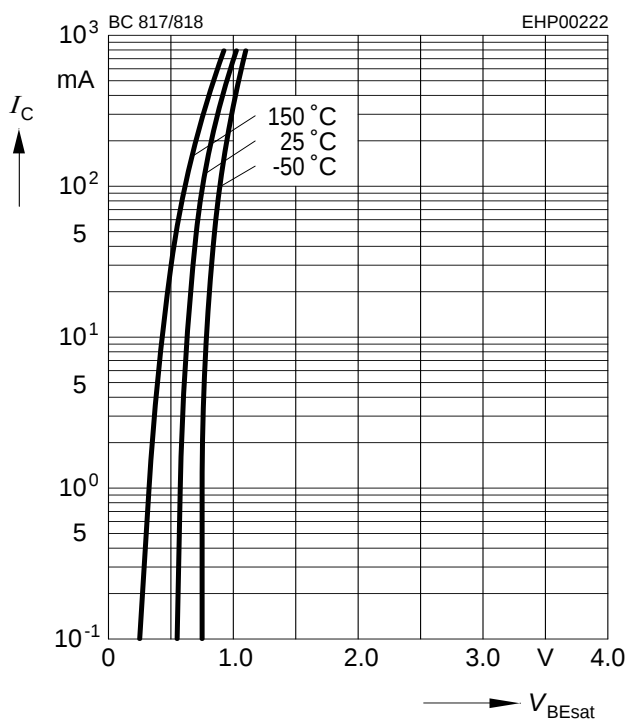
$$V_{CE} = 1 \text{ V}$$


**Collector-emitter saturation voltage**

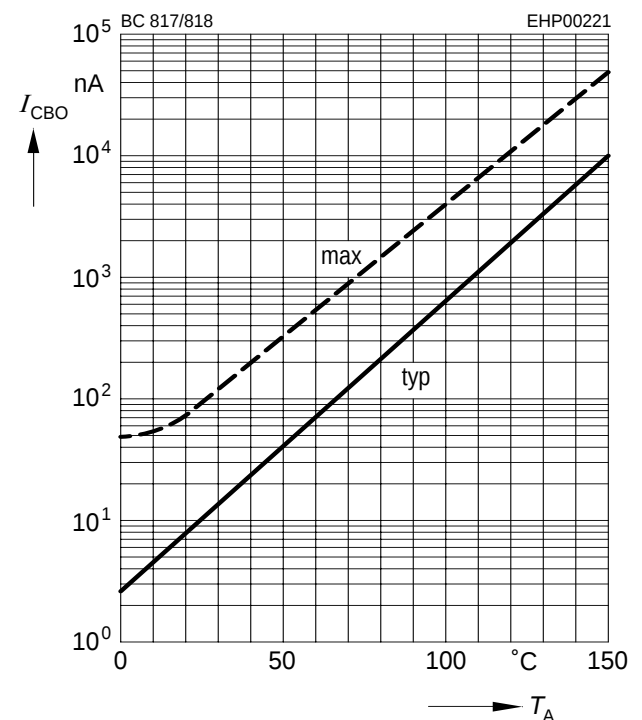
$$I_C = f(V_{CEsat}), h_{FE} = 10$$


**Base-emitter saturation voltage**

$$I_C = f(V_{BEsat}), h_{FE} = 10$$

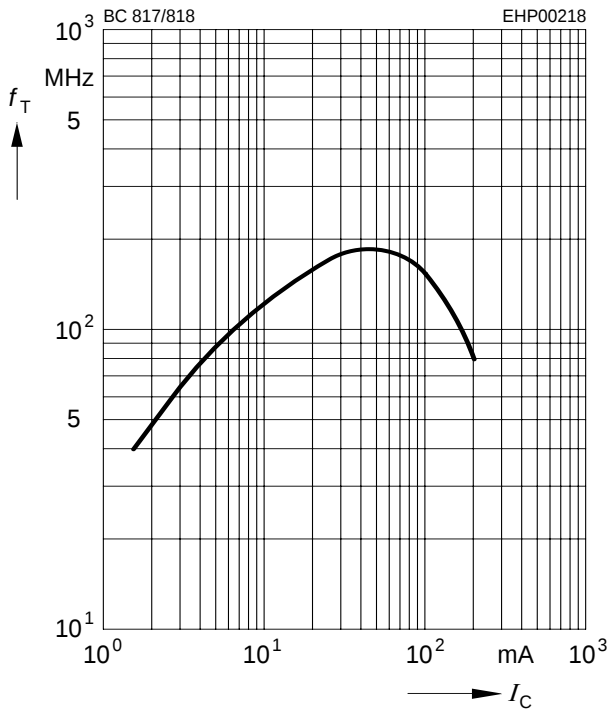

**Collector cutoff current  $I_{CBO} = f(T_A)$** 

$$V_{CBO} = 25 \text{ V}$$



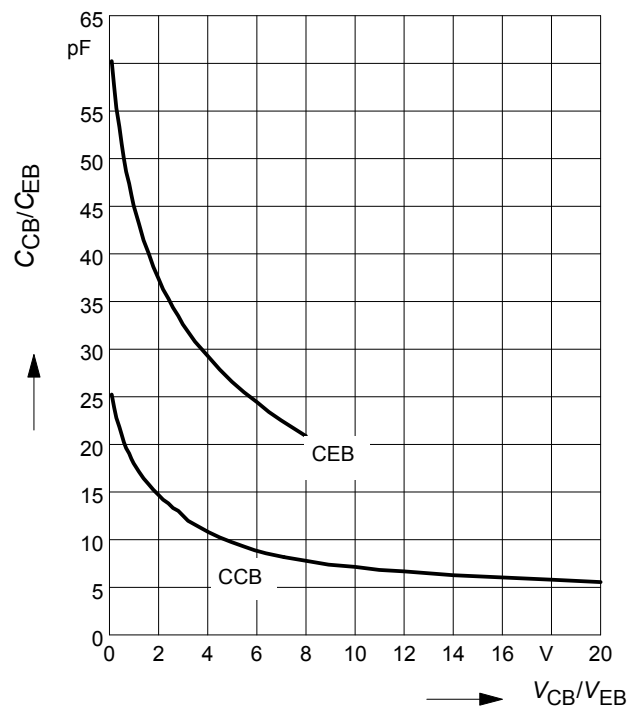
**Transition frequency  $f_T = f(I_C)$**

$V_{CE}$  = parameter in V,  $f = 2$  GHz



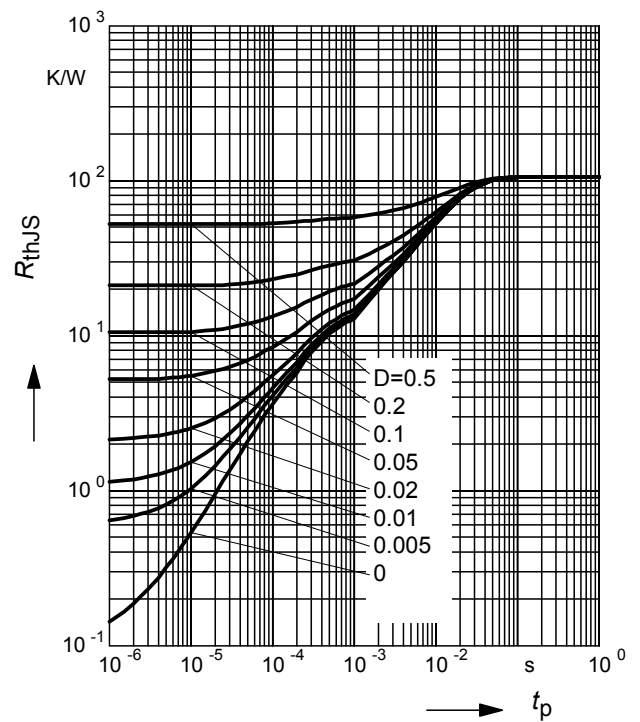
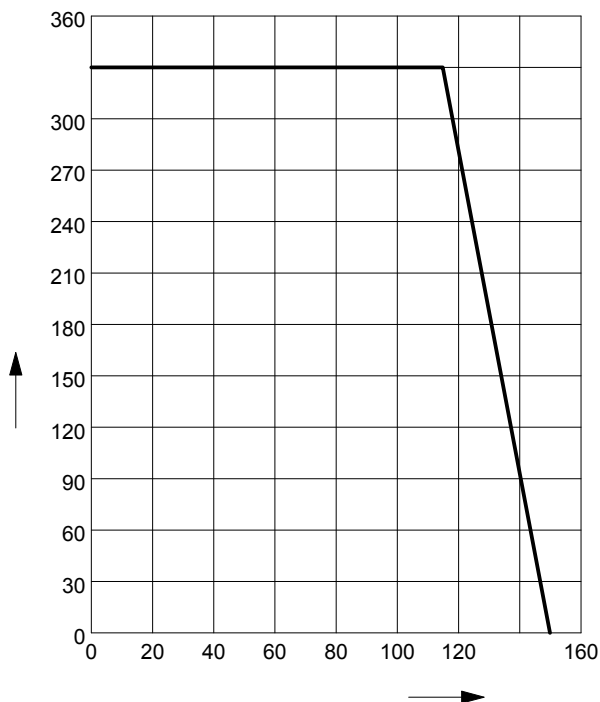
**Collector-base capacitance  $C_{cb} = f(V_{CB})$**

**Emitter-base capacitance  $C_{eb} = f(V_{EB})$**



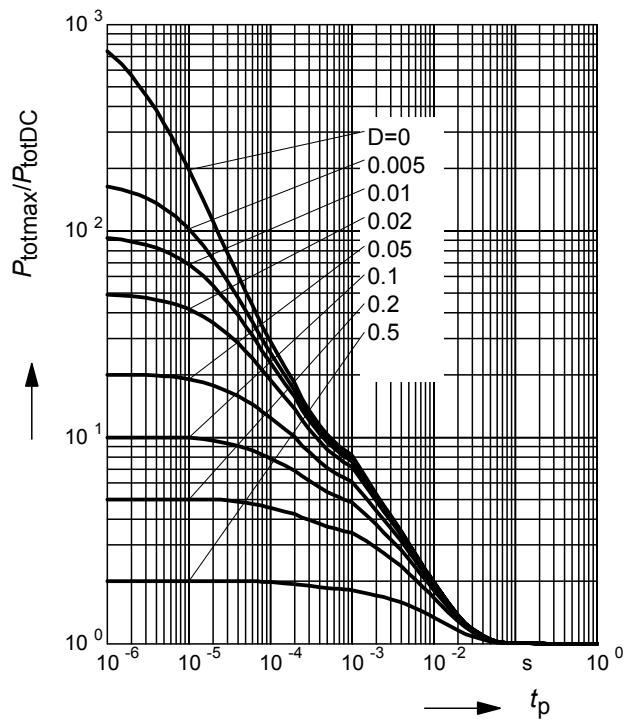
**Total power dissipation  $P_{tot} = f(T_S)$**

**Permissible Pulse Load  $R_{thJS} = f(t_p)$**

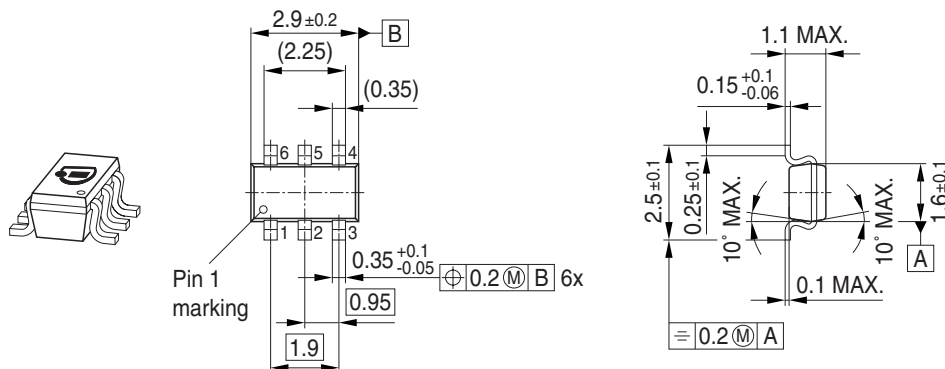


## Permissible Pulse Load

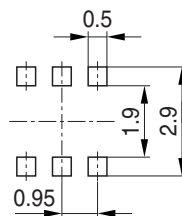
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$



## Package Outline

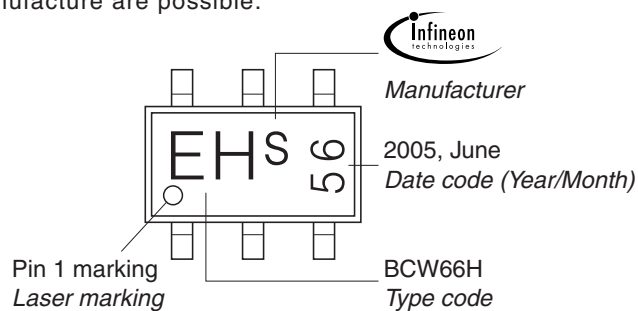


## Foot Print



## Marking Layout (Example)

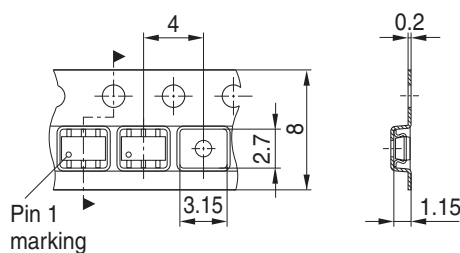
Small variations in positioning of Date code, Type code and Manufacture are possible.



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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